MAS3132E

Silicon epitaxial planar type

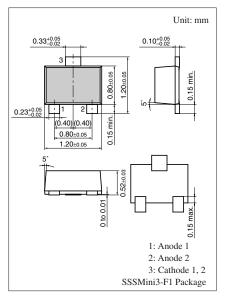
For high-speed switching circuits

Features

- Two elements are contained in one package, allowing highdensity mounting
- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t

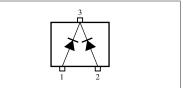
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter		Rating	Unit
Reverse voltage		80	V
Maximum peak reverse voltage		80	V
Single	I _F	100	mA
Double		150	
Single	I _{FM}	225	mA
Double		340	
Single	I _{FSM}	500	mA
Double		750	
Junction temperature		150	°C
Storage temperature		-55 to +150	°C
	Single Double Single Double Single	Single I _F Double I _{FM} Double Single I _{FM} Single I _{FSM}	$\begin{tabular}{ c c c c c c } \hline \mathbf{V}_{RM} & 80 \\ \hline \mathbf{Single} & \mathbf{I}_{F} & 100 \\ \hline \mathbf{Double} & 150 \\ \hline \mathbf{Single} & \mathbf{I}_{FM} & 225 \\ \hline \mathbf{Double} & 340 \\ \hline \mathbf{Single} & $\mathbf{I}_{\mathrm{FSM}}$ & 500 \\ \hline \mathbf{Double} & 750 \\ \hline \mathbf{T}_{j} & 150 \\ \hline \end{tabular}$



Marking Symbol: MU

Internal Connection



Note) *: t = 1 s

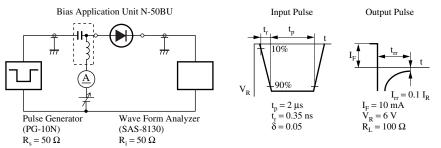
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	V _R	$I_R = 100 \ \mu A$	80			V
Reverse current	I _R	V _R = 75 V			100	nA
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$			2	pF
Reverse recovery time *	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
		$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$				

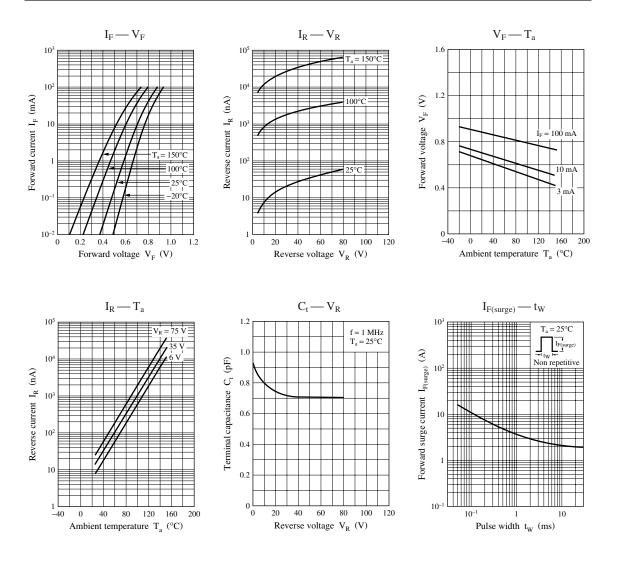
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.

2. Absolute frequency of input and output is 100 MHz.

3. *: t_{rr} measurement circuit



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